Customer Information Notification

2020010011

Issue Date: 18-Mar-2020
Effective Date: 19-Mar-2020

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QUALITY

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[ ] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[ ] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[X] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage
[ ] Firmware		[X] Other - Data Sheet Update for correction and clarification		

i.MXRT1060 Data Sheet Rev 0.2 and Errata Rev 1.1 Updates

Description

NXP Semiconductors announces errata update to revision 1.1 and data sheet update to revision 0.2 for i.MXRT1060. The revision history included in the updated documents provides a detailed description of the changes. Changes are summarized below.

For RT1060 Chip Errata:
Added following errata:
* ERR050235 CCM: Incorrect clock setting for CAN affects UART clock gating

For RT1060 Consumer DS, Data Sheet Changes:
1. Updated the SPI NAND Flash in the Section 1.1, Features
2. Updated the features of RT1062 in the Table 1, Ordering information
3. Updated the Table 81, Boot through UART1 and removed the Table, Boot through UART2
4. Updated the figure and table numbers in the Section 6.2, 12 x 12 mm package information
5. Updated the Figure 53, "10 x 10 mm BGA, case x package top, bottom, and side Views" and Figure 54, "12 x 12 mm BGA, case x package top, bottom, and side Views"

For RT1060 Industrial DS, Data Sheet Changes:
1. Updated the SPI NAND Flash in the Section 1.1, Features
2. Updated the Table 81, Boot through UART1 and removed the Table, Boot through UART2
3. Updated the figure and table numbers in the Section 6.2, 12 x 12 mm package information
4. Updated the Figure 53, "10 x 10 mm BGA, case x package top, bottom, and side Views" and Figure 54, "12 x 12 mm BGA, case x package top, bottom, and side Views"

The i.MXRT1060 errata revision 1.1 is attached to this notice, and can be found at:

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.
Data Sheet Revision
A new datasheet will be issued

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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Affected Part Numbers
MIMXRT1062CVL5A
MIMXRT1062DVL6A
MIMXRT1061CVJ5A
MIMXRT106LDVL6A
MIMXRT1062DVJ6A
MIMXRT106ADVL6A
MIMXRT106FDVL6A
MIMXRT1062CVJ5A